

## **BASICS OF ADHESIVE BONDING TECHNOLOGY**

FEBRUARY 28, 2024, GEMA BLANCO SIKA S.A.U. / TARGET MARKET INDUSTRY



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# INTRODUCTION, TERMS





## ADHESIVE AND BONDING

# Adhesive (DIN EN 923)

 Non-metallic material that can join parts by surface adhesion and internal strength

## Bonding technology (DIN EN ISO 9000)

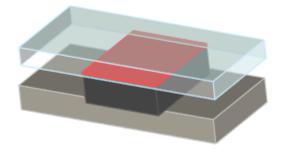
- Special process
- Implementation only by qualified personnel



# ADHESIVE AND BONDING ADHESION AND COHESION

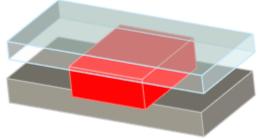
#### Adhesion

- Connection between adhesive and joined part due to chemical and physical bonding as well as mechanical anchoring
- Boundary layer (a few nm)



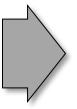
#### Cohesion

- Internal strength of the adhesive or part to be joined
- Whole material





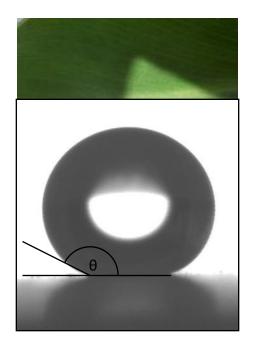
# ADHESIVE AND BONDING WETTING



Without wetting no adhesion

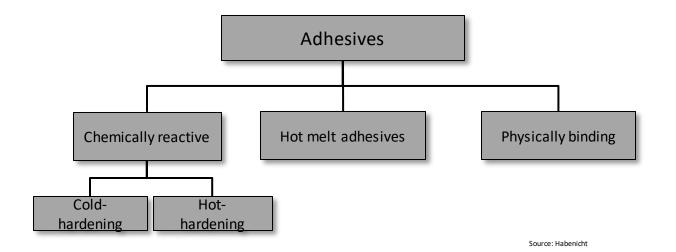
#### Obstruction of wetting by...

- Surface tension of the part to be joined is too low
- Surface roughness of the part to be joined is too high
- Too little adhesive



## **ADHESIVE AND BONDING**

## **CLASSIFICATION OF ADHESIVES**





# ADHESIVE AND BONDING CURING MECHANISMS

#### Chemical reaction

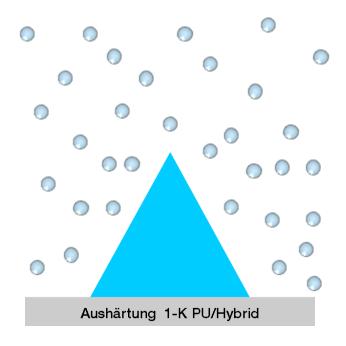
- 1-C moisture reactive
- 1-C Sika Booster
- 2-C systems

#### Physical setting

- Stiffen in the body (hot melt adhesives)
- evaporation, diffusion



# ADHESIVE AND BONDING CURING 1-C MOISTURE-REACTIVE



#### Advantages

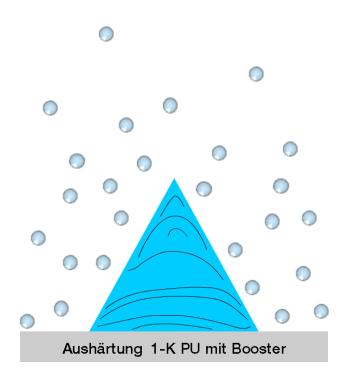
- Easy to dose
- Can be processed with simple equipment
- No mixing necessary
- Long open time

#### Disadvantages

- Curing (days)
- Dependent on humidity
- Limited joint dimension



# ADHESIVE AND BONDING CURING 1-C PUR / STP BOOSTER



#### **Advantages**

- Relatively fast curing (hours)
- Unlimited joint dimension
- Easy to change between application with and without booster (direct glazing)

#### Disadvantages

- Booster paste must be dosed and mixed
- Only applicable for selected products
- Relatively short open time



## ADHESIVE AND BONDING

## **CURING 2-C PUR**



#### Advantages

- Independent of humidity
- Large selection of products
- Curing (minutes)
- Independent joint geometry

#### Disadvantages

- A- and B- components must be dosed and mixed
- Open time versus curing time not independently adjustable
- Partly purging or cleaning effort in case of work interruption



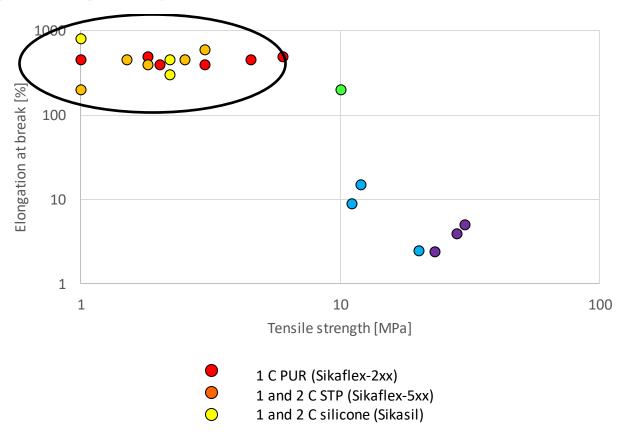
# **ELASTIC BONDING**





## **ELASTIC BONDING**

## PRODUCTS AT A GLANCE





# ELASTIC BONDING PRODUCT FEATURES

#### Features

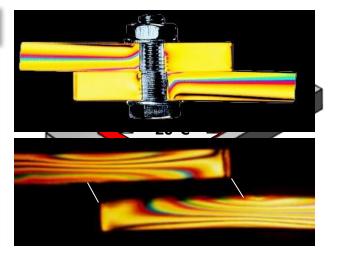
- Layer thickness > 3 mm (thick film adhesive)
- Large adhesive surface for the transmission of forces
- Mostly moisture-reactive 1 C products (PUR, STP, silicone)
- Application on metals, plastics, glass, coatings, etc.



# ELASTIC BONDING ADVANTAGES

#### Advantages due to high elongation

- Good tolerance compensation
- Suitability for joining different materials (thermal expansion)
- Bonding and sealing in one operation
- Uniform stress distribution



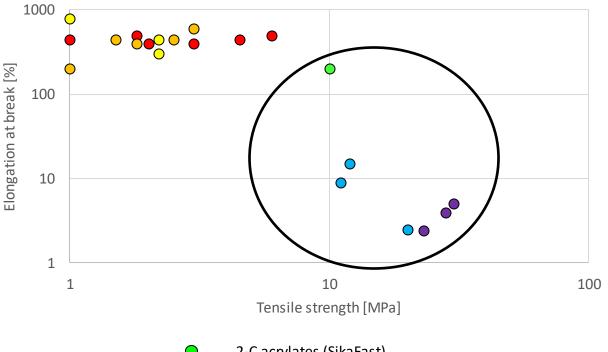
# RIGID BONDING





## **RIGID BONDING**

## PRODUCTS AT A GLANCE



- 2-C acrylates (SikaFast)
- 2-C PUR (SikaForce)
- 1- and 2-C epoxy (SikaPower)



# RIGID BONDING PRODUCT FEATURES

#### Features

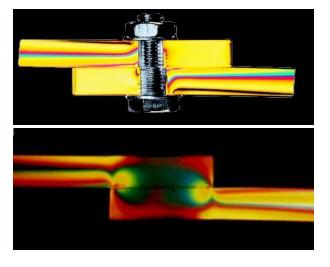
- Layer thicknesses < 3 mm (thin-film bonding)
- Small adhesive area for the transmission of forces
- Mostly 2-C products
- Application on metals, plastics, glass, coatings, etc.

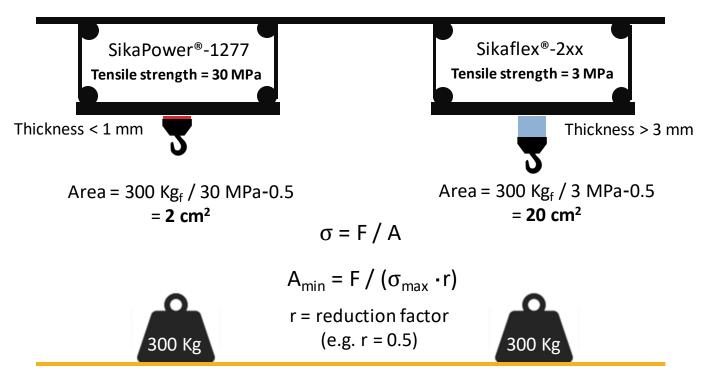


# RIGID BONDING ADVANTAGES

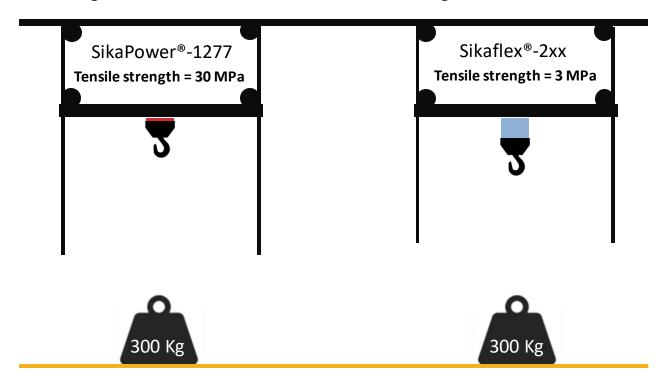
#### Advantages through ...

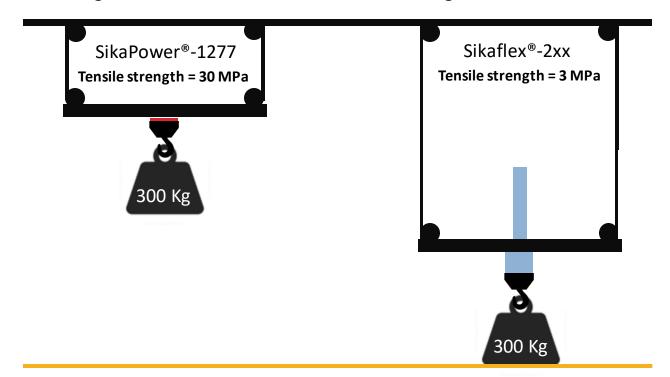
- No penetration of the parts to be joined
- Weight saving thanks to less material used
- Higher stiffness in the component

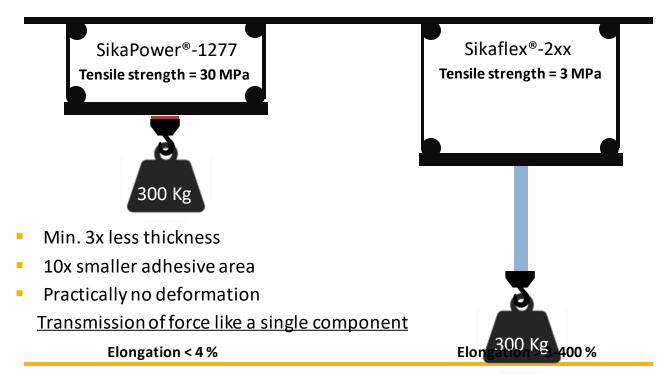












## **ADHESIVE SELECTION**





# ADHESIVE SELECTION PROCEDURE OF PRODUCT SELECTION

# Customer / Applicator Knowledge about application Defines stress Creates and updates specifications Specification sheet Supplier / Manufacturer Knowledge about products Defines stressabilty Proposes products according to specifications

## **ADHESIVE SELECTION**

## POSSIBLE CRITERIA FOR ADHESIVE SELECTION

#### Parts to be joined

#### Mechanics

#### Processing

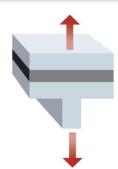
#### Endurance

- Material
- Adhesive surfaces
- Tolerances
- Thermal expansion

- Mechanical stress
- Mechanical loadbearing capacity
- Application equipment
- Cycle times
- Curing conditions
- Curing speed

- Temperature
- UV radiation
- Humidity
- Chemicals
- Fire behaviour











# **SURFACE TREATMENT**



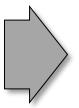


# SURFACE TREATMENT AIMS OF SURFACE TREATMENT

#### Improvement of..

- Adhesion
- Reproducibility
- Long-term resistance

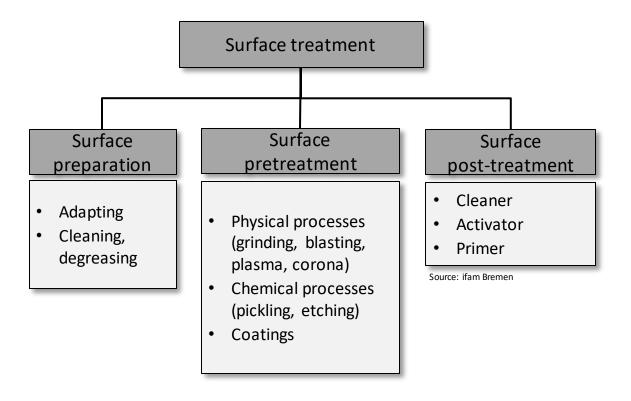
Source: ifam Bremen



Avoid mistakes, ensure security!



# SURFACE TREATMENT TYPES OF SURFACE TREATMENT



# SURFACE TREATMENT CLEANER

#### Features, properties

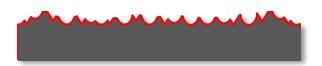
- Pre-treatment agent without reactive components
- Not film-forming
- Solvent, abrasive paste
- Application with wipe



# SURFACE TREATMENT ACTIVATOR

#### Features, properties

- Reactive pre-treatment agent that forms a bond with the substrate, primer or adhesive
- Transparent
- Application with wipe



# SURFACE TREATMENT PRIMER

#### Features, properties

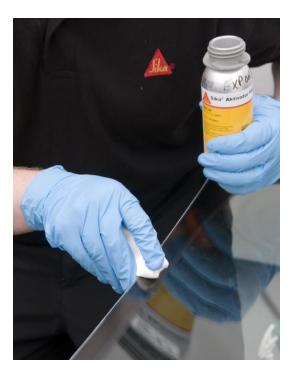
- Reactive pre-treatment agent that forms a bond with Activator and adhesive
- Film-forming (10 20 μm)
- Black, yellowish, transparent
- Application with foam, wool felt applicator, brush



# SURFACE TREATMENT SUMMARY

#### Key points

- Define suitable pre-treatment
- Keep surface quality constant
- Correct application method
- Observe flash-off times and temperature ranges
- Do not use third party products



# **APPLICATION**





# APPLICATION WORKFLOW





# APPLICATION ATTENTION

#### Attention!

- Adhesion promoters and primers that have not completely flashed off can block the curing mechanism of the PUR
- Flash-off times must be extended for absorbent, coarse-pored substrates and at temperatures below 10º C



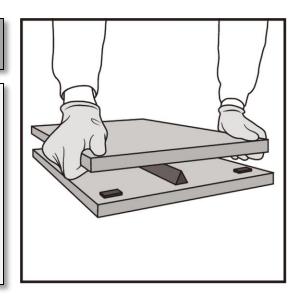




# APPLICATION BONDING

#### Bonding

- Join parts before skin formation / elapse of open time
- Immediately after joining, remove excess / tool the joint if necessary
- Ensure that the adhesive receives humidity (1-C Systems)







## APPLICATION DURING AND AFTER BONDING

### During and after bonding

- Remove adhesive contaminations with Sika Remover-208
- Remove adhesive contaminations on hands with Sika Cleaner-350 H
- Remove masking tapes immediately after joining and remove of excess







### WORKPLACE





# WORKPLACE THE WORKING AREA 1

### Principles / Prerequisites

- Observe temperature and humidity and adjust if necessary (optimal 15° - 25°C / 50%)
- Separate bonding from other processes
- Equipment according to the requirements



### WORKPLACE THE WORKING AREA 2

#### **Environment and safety**

- Bonding = handling of chemical products
- Ensure good ventilation
- Wear protective gloves
- Wear safety goggles
- No smoking, no fire, no food
- Correct disposal of waste and residues
- Preparation for emergencies











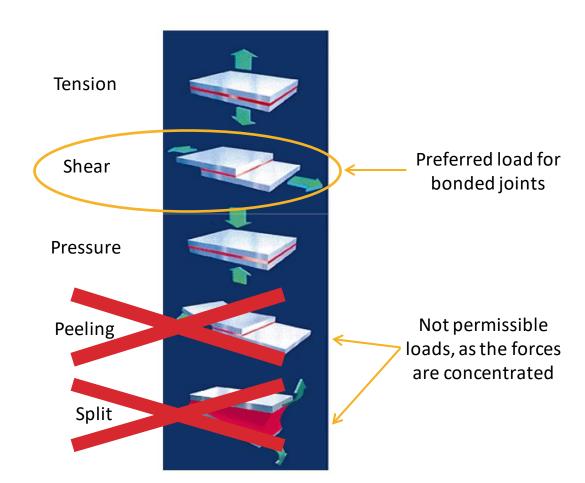


### **QUALITY CONTROL**





### **DIFFERENT TYPES OF LOADS**





## QUALITY CONTROL RESPONSIBILITIES

- Product quality
- Adhesion and compatibility tests
- Application guidelines
- Documents (PDB, SDB)





#### **Specification**

- Specifications
- Working instructions

#### **Application**

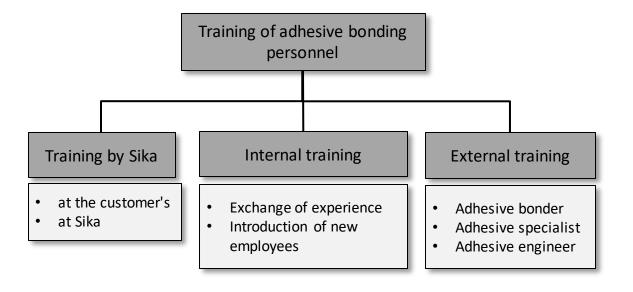
- Substrate treatment
- Correct application
- Complete documentation
- Quality control on site







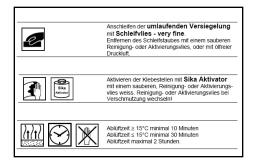
## QUALITY CONTROL TRAINING FOR ADHESIVE BONDING PERSONNEL



### QUALITY CONTROL DOCUMENTATION OF THE BONDING PROCESS

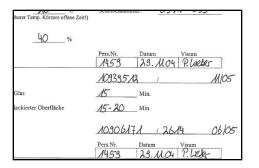
#### Working instructions

- Description of all work steps
- Definition of the materials to be used, aids



#### Adhesion protocol

- Confirmation of all work steps
- Documentation of materials used (batch numbers) and conditions





## QUALITY CONTROL FURTHER DOCUMENTS

#### Documents from Sika

- Product data sheets
- Safety data sheets
- General guidelines
- Additional Product Information (API)
- Additional Technical Information (ATI)







### THANK YOU FOR YOUR ATTENTION

